

## SURFACE MOUNT FAST RECOVERY RECTIFIER

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ Idea for printed circuit board
- ◆ Open Junction chip
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed:  
250 °C/ 10 seconds at terminals
- ◆ Glass passivated chip junction

### Mechanical Data

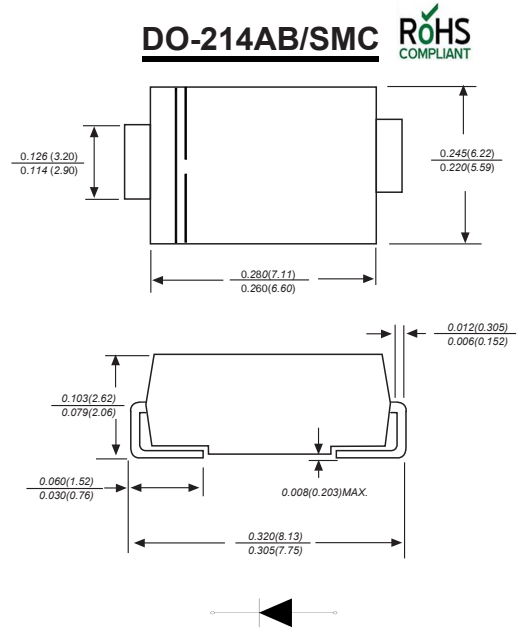
**Case :** JEDEC DO-214AB/SMC Molded plastic body

**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any

**Weight :** 0.0077 ounce, 0.22 grams



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	RS3AC	RS3BC	RS3DC	RS3GC	RS3JC	RS3KC	RS3MC	UNITS
		MDD RS3AC	MDD RS3BC	MDD RS3DC	MDD RS3GC	MDD RS3JC	MDD RS3KC	MDD RS3MC	
Maximum repetitive peak reverse voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	$I_{(AV)}$	3.0							A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	90							A
Maximum instantaneous forward voltage at 3.0A	$V_F$	1.30							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	$I_R$	5.0 100.0							$\mu\text{A}$
Maximum reverse recovery time (NOTE 1)	$t_{rr}$	150			250		500		ns
Typical junction capacitance (NOTE 2)	$C_J$	40.0							pF
Typical thermal resistance (NOTE 3)	$R_{\theta JA}$ $R_{\theta JC}$	45.0 15.0							$^\circ\text{C}/\text{W}$
Operating junction and storage temperature range	$T_J, T_{STG}$	-55 to +150							$^\circ\text{C}$

**Note:** 1. Reverse recovery condition  $I_F=0.5\text{A}, I_R=1.0\text{A}, t_{rr}=0.25\text{A}$   
 2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.  
 3. P.C.B. mounted with 2.0"x2.0" (5.0x5.0cm) copper pad areas

## Ratings And Characteristic Curves

Fig.1 Maximum Average Forward Current Rating

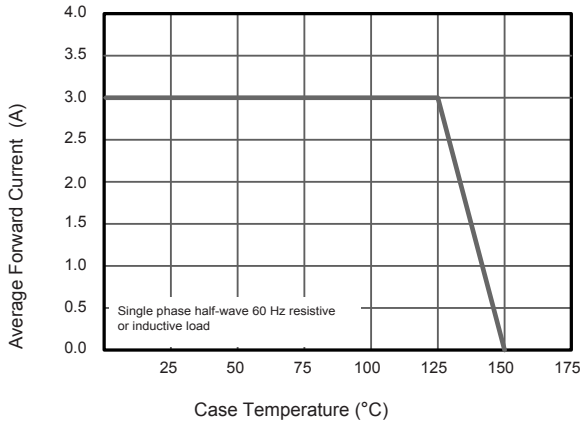


Fig.2 Typical Reverse Characteristics

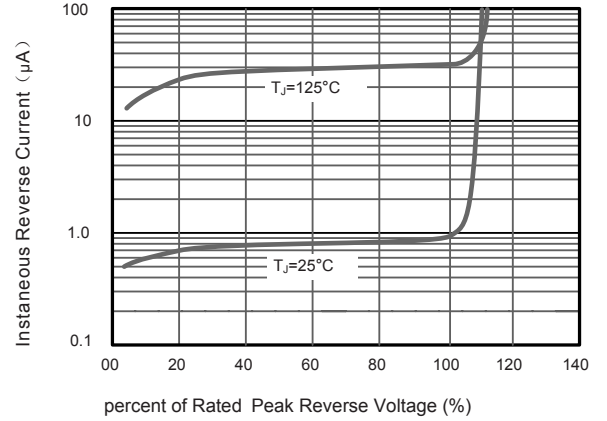


Fig.3 Typical Instantaneous Forward Characteristics

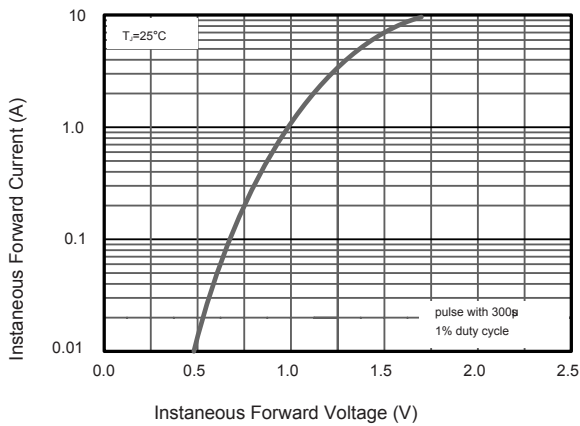


Fig.4 Typical Junction Capacitance

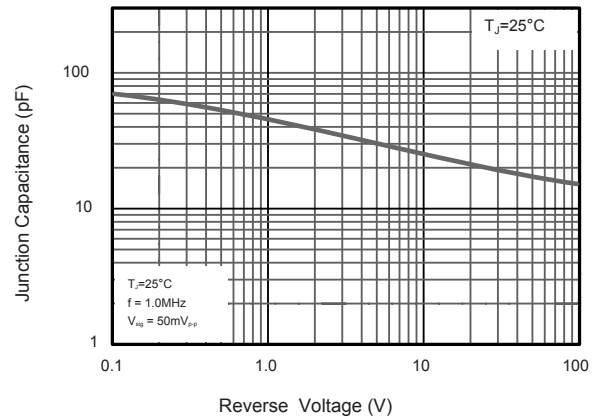
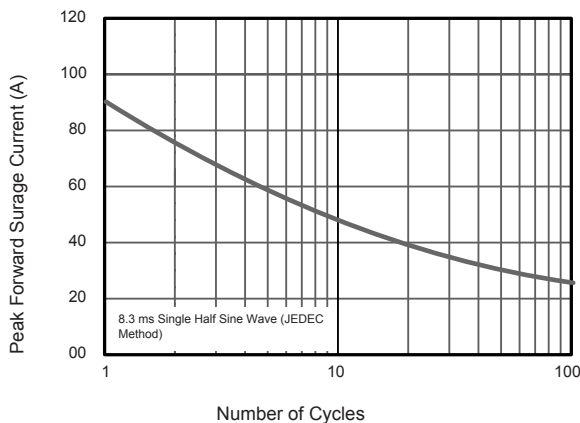
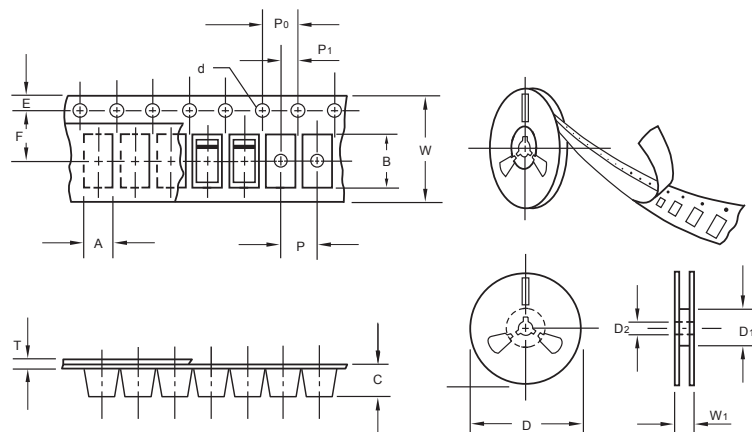


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



The curve above is for reference only.

## Packing information



unit:mm

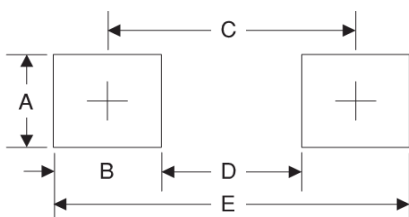
Item	Symbol	Tolerance	SMC
Carrier width	A	0.1	6.15
Carrier length	B	0.1	8.41
Carrier depth	C	0.1	2.42
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D <sub>1</sub>	min	50.00
Feed hole diameter	D <sub>2</sub>	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P <sub>0</sub>	0.1	4.00
Embossment center	P <sub>1</sub>	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	16.00
Reel width	W <sub>1</sub>	1.0	16.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

## Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC	13"	3,000	4.0	6000	190*190*41	330	365*365*340	42000	14.0

## Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	4.3	0.170
B	4.1	0.160
C	7.9	0.311
D	3.8	0.150
E	12	0.472